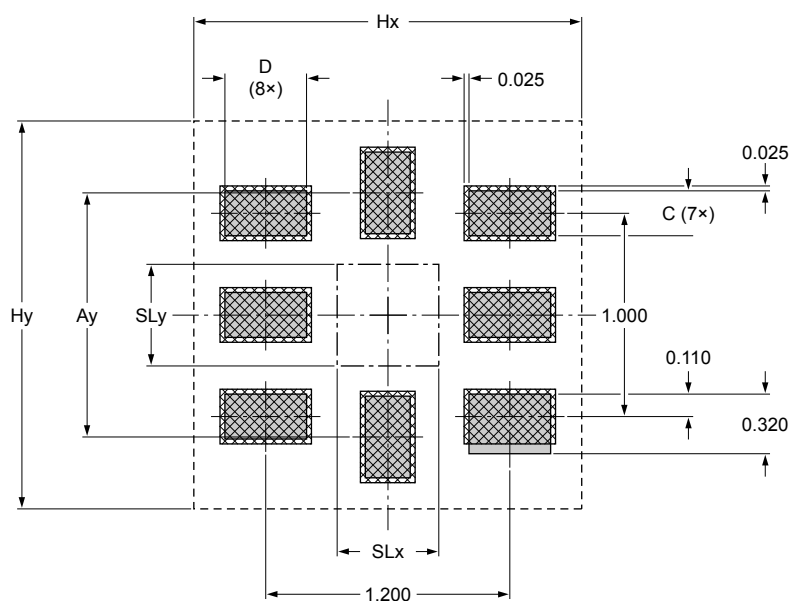





Footprint information for reflow soldering of XQFN8 package

SOT902-3



-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

DIMENSIONS in mm

Ay	C	D	SLx	SLy	Hx	Hy
1.2	0.22	0.4	0.5	0.5	1.9	1.9

Issue date 12-12-19
13-01-02

sot902-3_fr